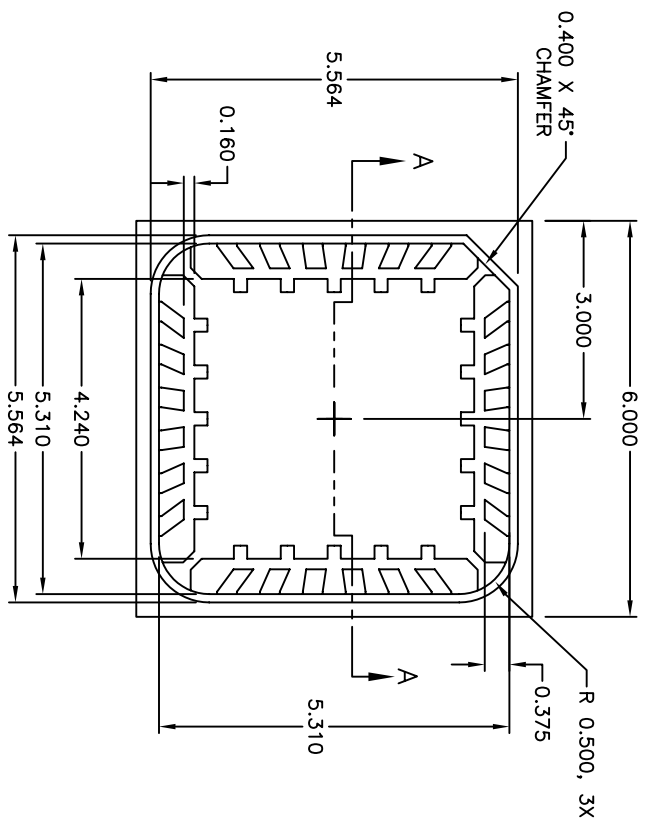


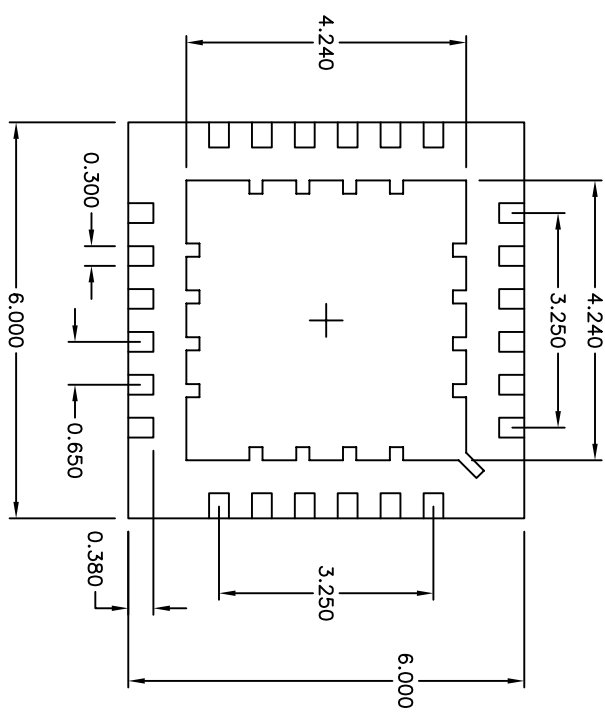
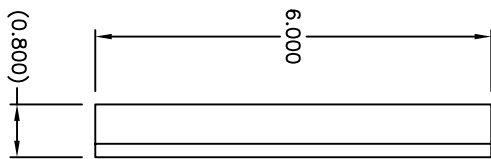
2

1

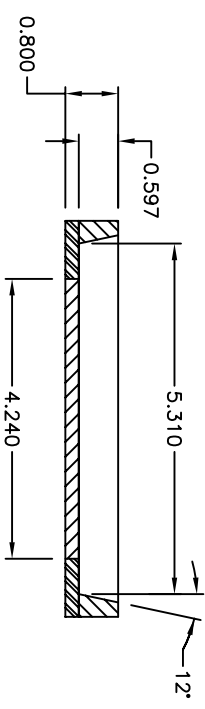
| SEMPAC REVISIONS | | |
|------------------|----------|--------------------|
| EON NO. | DATE | DESCRIPTION |
| 10766 | 10/20/06 | PRODUCTION RELEASE |
| | | APPROVED |
| | | D.MORRIS |



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 4.240mm X 4.240mm.
 6. JEDEC OUTLINE: MO-220 (VJJC-1).



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
 TOLERANCES ARE: X.XXX ±.015 X.XXXX ±.005
 ANGLES: ± 1°
 DO NOT SCALE DRAWING

| | | | |
|----------|--------------|------|----------|
| DRAWN BY | C. CRUZ | DATE | 10/20/06 |
| APP BY | P. FLASKERUD | DATE | 10/20/06 |
| CUSTOMER | --- | | |

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 PHONE: (408) 400-9002 FAX: (408) 400-9006

24 LEAD 6mm X 6mm
 MLP Open-Pak

| | | |
|-------|------------------------|-----|
| SIZE | PART NO. | REV |
| A | MLP6X6-24-OP-01 | 2 |
| SCALE | NONE | |
| FILE | MLP6X6-24-OP-01-R2.DWG | |
| SHEET | 1 OF 1 | |

2

1